NextFlex Project Abstract
Uniqarta, Inc.
Enabling Ultra-Thin Die Assembly at the NextFlex Hub

This project will enable an ultra-thin die assembly capability at the NextFlex Hub based on Uniqarta's FlexChip™ technology. The key objectives of this project are as follows:

- Develop a die-level thinning & assy capability for prototyping
- Benchmark the FlexChip ultra-thin die assembly process on an automated die tool
- Evaluate the electrical performance impact of the assembly process
- Transfer the FlexChip ultra-thin die assy capability to the NextFlex Hub

Partners collaborating with Uniqarta on this project are Jabil Circuit, UMass Amherst, and North Dakota State University.